

# EH1345HSTS-1.8432M



## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 8 Pin DIP Metal Thru-Hole 1.8432MHz  $\pm 50$ ppm 0°C to +70°C

## ELECTRICAL SPECIFICATIONS

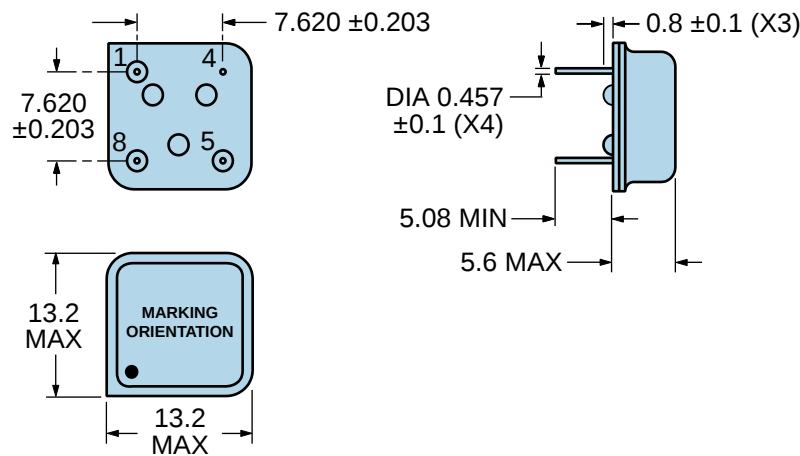
|                                       |                                                                                                                                                                                                                                       |
|---------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Nominal Frequency                     | 1.8432MHz                                                                                                                                                                                                                             |
| Frequency Tolerance/Stability         | $\pm 50$ ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, 1st Year Aging at 25°C, Shock, and Vibration.) |
| Aging at 25°C                         | $\pm 5$ ppm/year Maximum                                                                                                                                                                                                              |
| Operating Temperature Range           | 0°C to +70°C                                                                                                                                                                                                                          |
| Supply Voltage                        | 3.3Vdc $\pm 10\%$                                                                                                                                                                                                                     |
| Input Current                         | 35mA Maximum (No Load)                                                                                                                                                                                                                |
| Output Voltage Logic High (Voh)       | 2.7Vdc Minimum (IOH = -8mA)                                                                                                                                                                                                           |
| Output Voltage Logic Low (Vol)        | 0.5Vdc Maximum (IOL = +8mA)                                                                                                                                                                                                           |
| Rise/Fall Time                        | 6nSec Maximum (Measured at 20% to 80% of waveform)                                                                                                                                                                                    |
| Duty Cycle                            | 50 $\pm 10\%$ (Measured at 50% of waveform)                                                                                                                                                                                           |
| Load Drive Capability                 | 30pF Maximum                                                                                                                                                                                                                          |
| Output Logic Type                     | CMOS                                                                                                                                                                                                                                  |
| Pin 1 Connection                      | Tri-State (Disabled Output: High Impedance)                                                                                                                                                                                           |
| Tri-State Input Voltage (Vih and Vil) | 70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output (High Impedance), No Connect to enable output.                                                                                                              |
| Absolute Clock Jitter                 | $\pm 250$ pSec Maximum, $\pm 100$ pSec Typical                                                                                                                                                                                        |
| One Sigma Clock Period Jitter         | $\pm 50$ pSec Maximum, $\pm 40$ pSec Typical                                                                                                                                                                                          |
| Start Up Time                         | 10mSec Maximum                                                                                                                                                                                                                        |
| Storage Temperature Range             | -55°C to +125°C                                                                                                                                                                                                                       |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |                                       |
|------------------------------|---------------------------------------|
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C |
| Lead Integrity               | MIL-STD-883, Method 2004              |
| Mechanical Shock             | MIL-STD-202, Method 213, Condition C  |
| Resistance to Soldering Heat | MIL-STD-202, Method 210               |
| Resistance to Solvents       | MIL-STD-202, Method 215               |
| Solderability                | MIL-STD-883, Method 2003              |
| Temperature Cycling          | MIL-STD-883, Method 1010              |
| Vibration                    | MIL-STD-883, Method 2007, Condition A |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION                 |
|-----|----------------------------|
| 1   | Tri-State (High Impedance) |
| 4   | Case/Ground                |
| 5   | Output                     |
| 8   | Supply Voltage             |

| LINE | MARKING                                                                                     |
|------|---------------------------------------------------------------------------------------------|
| 1    | ECLIPTEK                                                                                    |
| 2    | EH13TS<br>EH13=Product Series                                                               |
| 3    | 1.8432M                                                                                     |
| 4    | XXYYZZ<br>XX=Ecliptek Manufacturing Code<br>Y=Last Digit of the Year<br>ZZ=Week of the Year |

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OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external 0.1 $\mu$ F low frequency tantalum bypass capacitor in parallel with a 0.01 $\mu$ F high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

|                                                     |                                      |
|-----------------------------------------------------|--------------------------------------|
| T <sub>S</sub> MAX to T <sub>L</sub> (Ramp-up Rate) | 3°C/Second Maximum                   |
| Preheat                                             |                                      |
| - Temperature Minimum (T <sub>S</sub> MIN)          | 150°C                                |
| - Temperature Typical (T <sub>S</sub> TYP)          | 175°C                                |
| - Temperature Maximum (T <sub>S</sub> MAX)          | 200°C                                |
| - Time (t <sub>S</sub> MIN)                         | 60 - 180 Seconds                     |
| Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )    | 3°C/Second Maximum                   |
| Time Maintained Above:                              |                                      |
| - Temperature (T <sub>L</sub> )                     | 217°C                                |
| - Time (t <sub>L</sub> )                            | 60 - 150 Seconds                     |
| Peak Temperature (T <sub>P</sub> )                  | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (T <sub>P</sub> Target)     | 250°C +0/-5°C                        |
| Time within 5°C of actual peak (t <sub>P</sub> )    | 20 - 40 Seconds                      |
| Ramp-down Rate                                      | 6°C/Second Maximum                   |
| Time 25°C to Peak Temperature (t)                   | 8 Minutes Maximum                    |
| Moisture Sensitivity Level                          | Level 1                              |

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 185°C

|                                     |                            |
|-------------------------------------|----------------------------|
| Ts MAX to Tl (Ramp-up Rate)         | 5°C/Second Maximum         |
| Preheat                             |                            |
| - Temperature Minimum (Ts MIN)      | N/A                        |
| - Temperature Typical (Ts TYP)      | 150°C                      |
| - Temperature Maximum (Ts MAX)      | N/A                        |
| - Time (ts MIN)                     | 60 - 120 Seconds           |
| Ramp-up Rate (Tl to Tp)             | 5°C/Second Maximum         |
| Time Maintained Above:              |                            |
| - Temperature (Tl)                  | 150°C                      |
| - Time (tL)                         | 200 Seconds Maximum        |
| Peak Temperature (Tp)               | 185°C Maximum              |
| Target Peak Temperature (Tp Target) | 185°C Maximum 2 Times      |
| Time within 5°C of actual peak (tp) | 10 Seconds Maximum 2 Times |
| Ramp-down Rate                      | 5°C/Second Maximum         |
| Time 25°C to Peak Temperature (t)   | N/A                        |
| Moisture Sensitivity Level          | Level 1                    |

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Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

|                                     |                                                       |
|-------------------------------------|-------------------------------------------------------|
| Ts MAX to Tl (Ramp-up Rate)         | 5°C/Second Maximum                                    |
| Preheat                             |                                                       |
| - Temperature Minimum (Ts MIN)      | N/A                                                   |
| - Temperature Typical (Ts TYP)      | 150°C                                                 |
| - Temperature Maximum (Ts MAX)      | N/A                                                   |
| - Time (ts MIN)                     | 30 - 60 Seconds                                       |
| Ramp-up Rate (Tl to Tp)             | 5°C/Second Maximum                                    |
| Time Maintained Above:              |                                                       |
| - Temperature (Tl)                  | 150°C                                                 |
| - Time (tL)                         | 200 Seconds Maximum                                   |
| Peak Temperature (Tp)               | 245°C Maximum                                         |
| Target Peak Temperature (Tp Target) | 245°C Maximum 1 Time / 235°C Maximum 2 Times          |
| Time within 5°C of actual peak (tp) | 5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times |
| Ramp-down Rate                      | 5°C/Second Maximum                                    |
| Time 25°C to Peak Temperature (t)   | N/A                                                   |
| Moisture Sensitivity Level          | Level 1                                               |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.